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SERIAL NUMBER 10/735,355	FILING DATE 12/12/2003 RULE	CLASS 257	GROUP ART UNIT 2812	ATTORNEY DOCKET NO. MI22-2457
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APPLICANTS

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** CONTINUING DATA *****

This application is a DIV of 10/340,126 01/10/2003 PAT 6,864,155
 which is a DIV of 10/051,981 01/16/2002

yes JH

yes JH

** FOREIGN APPLICATIONS *****

none JH

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 03/23/2004

Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged Examiner's Signature: <u>J. Kennedy</u> Initials: <u>JK</u>	ID	3	14	1

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TITLE

Wafer Bonding Method Of Forming Silicon-On-Insulator Comprising Integrated Circuitry

FILING FEE RECEIVED 770	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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